



503.37770X00

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: M. OGINO, et al.
Serial No.: 09/429,297
Filed: October 28, 1999
For: SEMICONDUCTOR DEVICE, SEMICONDUCTOR WAFER,
SEMICONDUCTOR MODULE, AND A METHOD OF
MANUFACTURING SEMICONDUCTOR DEVICE
Group: 2822
Examiner: James M. Mitchell

AMENDMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

December 10, 2002

Sir:

In response to the Office Action mailed July 10, 2002, please amend the
above-identified application as follows:

IN THE CLAIMS:

Please amend the claims presently in the application as follows:

02/26/2003 SSURLES 00000005 212135 (Twice Amended) A semiconductor device comprising:

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a semiconductor chip,

a porous stress relaxing layer provided on a plane, whereon circuits

and electrodes are formed, of said semiconductor chip,

a circuit layer provided on said stress relaxing layer and connected to

said electrodes, and

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